

PLATING METHOD

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Abstract

PURPOSE: To remove the bubbles deposited on an object to be plated and to stably plate the object by allowing a plating soln. to flow at a high speed.

CONSTITUTION: A plating soln. L is supplied to a plating device 1 from the funneled part 2s at its bottom, and allowed to overflow from the upper opening 2p. A cathode 5 is clamped between a wafer U and an elastic member 4. The plating soln. moves upward through a through-hole 6h of an anode. When an object on the receiving part 3 extending inwardly at the opening 2p is plated, the plating soln. is allowed to flow at a high speed for 15sec from the start to remove the bubbles. The electric current direction is specified at this time, because the plating soln. L flows unidirectionally and distortion is caused. Plating is then applied for 10min at a standard flow velocity, the current is stopped for 5sec while maintaining the high flow velocity to remove bubbles, and the cyclic process is repeated.

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